# **RENESAS** 2SA1029, 2SA1030

Silicon PNP Epitaxial

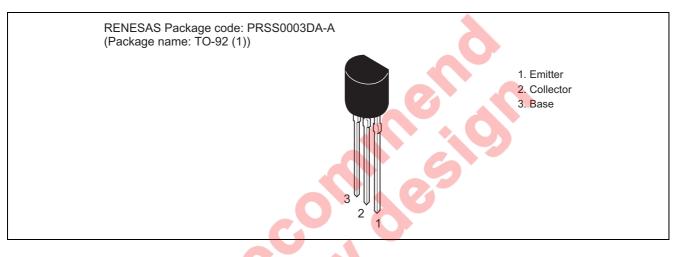
REJ03G0633-0300 (Previous ADE-208-1004A) Rev.3.00 Aug.10.2005

2500

## Application

- Low frequency amplifier
- Complementary pair with 2SC458 and 2SC2308

### Outline



## Absolute Maximum Ratings

				$(Ta = 25^{\circ}C)$
Item	Symbol	2SA1029	2SA1030	Unit
Collector to base voltage	V <sub>CBO</sub>	-30	-55	V
Collector to emitter voltage	V <sub>CEO</sub>	-30	-50	V
Emitter to base voltage	V <sub>EBO</sub>	-5	-5	V
Collector current	Ic	-100	-100	mA
Emitter current	Ι <sub>Ε</sub>	100	100	mA
Collector power dissipation	Pc	300	300	mW
Junction temperature	Tj	150	150	°C
Storage temperature	Tstg	-55 to +150	-55 to +150	°C



## **Electrical Characteristics**

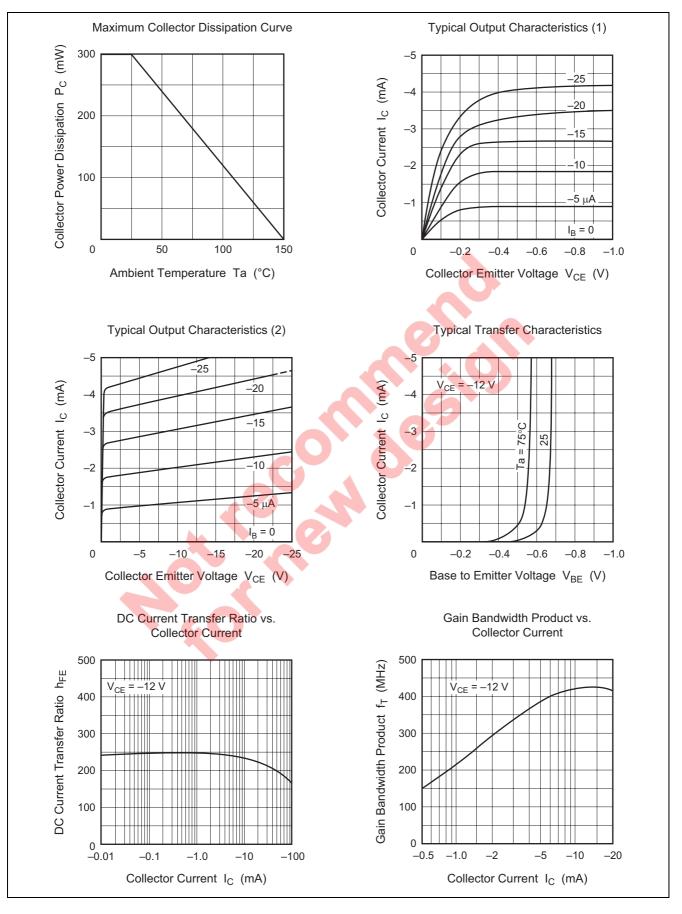
 $(Ta = 25^{\circ}C)$ 

		2SA1029 2SA1030							
Item	Symbol	Min	Тур	Max	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	V <sub>(BR)CBO</sub>	-30	-	—	-55	-	—	V	$I_{\rm C} = -10 \ \mu A, \ I_{\rm E} = 0$
Collector to emitter breakdown voltage	V <sub>(BR)CEO</sub>	-30	_	—	-50	_	—	V	$I_{C} = -1 \text{ mA}, \text{ R}_{BE} = \infty$
Emitter to base breakdown voltage	V <sub>(BR)EBO</sub>	-5	_	—	-5	_	—	V	$I_E = -10 \ \mu A, \ I_C = 0$
Collector cutoff current	I <sub>CBO</sub>	_	_	-0.5	—	_	-0.5	μΑ	$V_{CB} = -18 \text{ V}, I_E = 0$
Emitter cutoff current	I <sub>EBO</sub>	_	_	-0.5	_	_	-0.5	μA	$V_{EB} = -2 V, I_C = 0$
DC current trnsfer ratio	h <sub>FE</sub> * <sup>1</sup>	100	_	500	100	_	320		$V_{CE} = -12 \text{ V},$ $I_C = -2 \text{ mA}$
Base to emitter voltage	V <sub>BE</sub>			-0.8	_		-0.8	V	$V_{CE} = -12 \text{ V},$ $I_C = -2 \text{ mA}$
Collector to emitter saturation voltage	V <sub>CE(sat)</sub>			-0.2	_	-	-0.2	V	$I_{\rm C} = -10$ mA, $I_{\rm B} = -1$ mA
Gain bandwidth product	f⊤	200	280	_	200	280		MHz	$V_{CB} = -12 \text{ V},$ $I_{C} = -2 \text{ mA}$
Collector output capacitance	Cob		3.3	4.0		3.3	4.0	pF	V <sub>CB</sub> = –10 V, I <sub>E</sub> = 0, f = 1 MHz

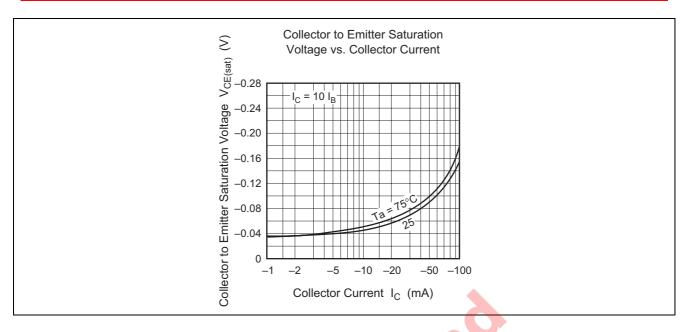
capacitance								
Note: 1. The 2SA1029 and 2SA1030 are grouped by hre as follows.								
	В	С		D				
2SA1029	100 to 200	160 to 32	20 25	50 to 500				
2SA1030	100 to 200	160 to 32	20 —			Č 💊	(5)	
					3			



### **Main Characteristics**

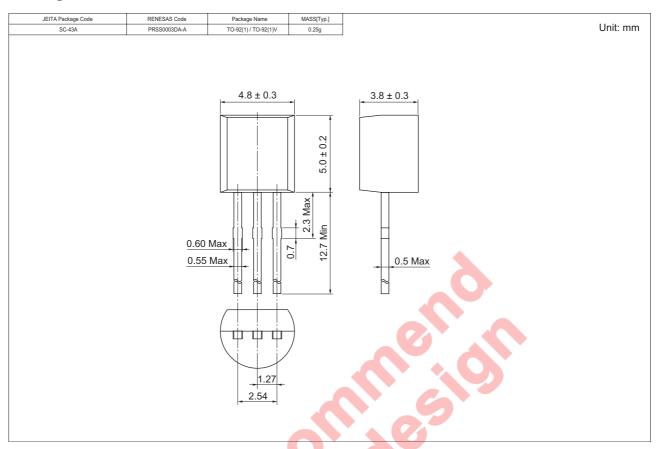








## **Package Dimensions**



## **Ordering Information**

Part Name	Quantity	Shipping Container
2SA1029BTZ	2500	Hold Box, Radial Taping
2SA1029CTZ		
2SA1029DTZ		
2SA1030BTZ		
2SA1030CTZ		

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.



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